

ABSTRACT OF THE DISCLOSURE

A plurality of chips arranged in the same scanning row of a wafer is divided into groups, which include a predetermined number of chips. The images of the chips in each group are compared with each other in the double detection. If one group includes the first, the second and the third chips; the first chip and the second chip are compared, then the first chip and the third chip are compared, and at last, the second chip and the third chip are compared while the images are captured. It is therefore possible to detect the defects in the double detection for all the chips including peripheral chips by comparing the images for the same number of comparison times as the number of chips.